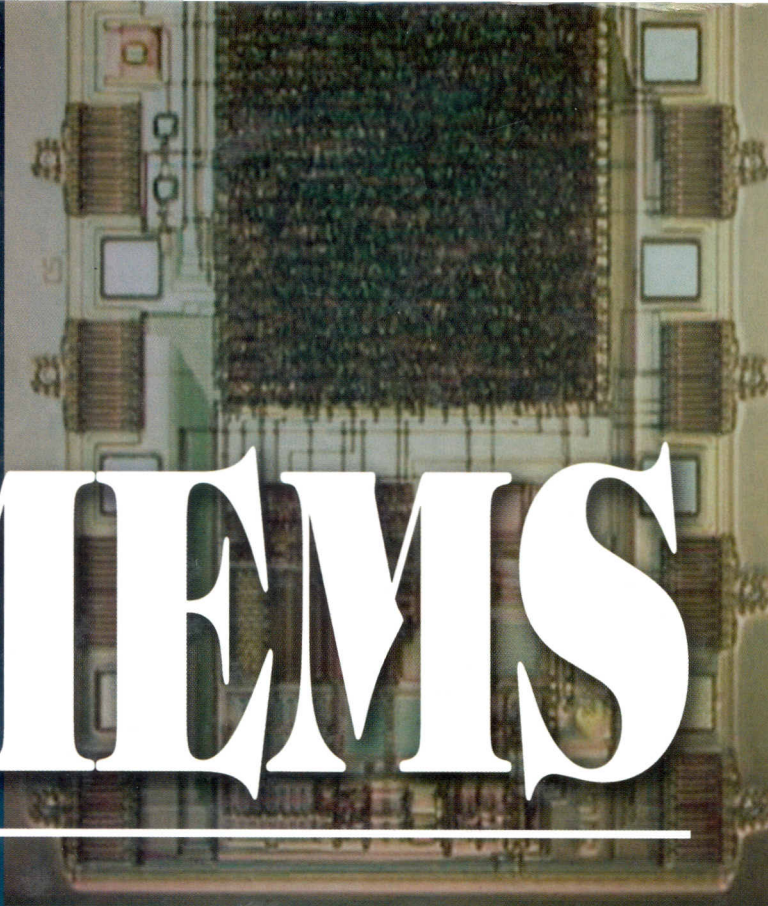


A detailed, high-magnification photograph of a micro-electro-mechanical systems (MEMS) chip. The chip is rectangular and features a complex array of small, square, and rectangular structures, likely actuators or sensors, arranged in a grid-like pattern. The structures are interconnected by fine lines, and the overall color palette is dominated by shades of green, brown, and gold, typical of semiconductor manufacturing.

MEMS

a practical
guide to
design, analysis
and applications

edited by

Jan G. Korvink
Oliver Paul

MICRO-ELECTRO-MECHANICAL SYSTEMS

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